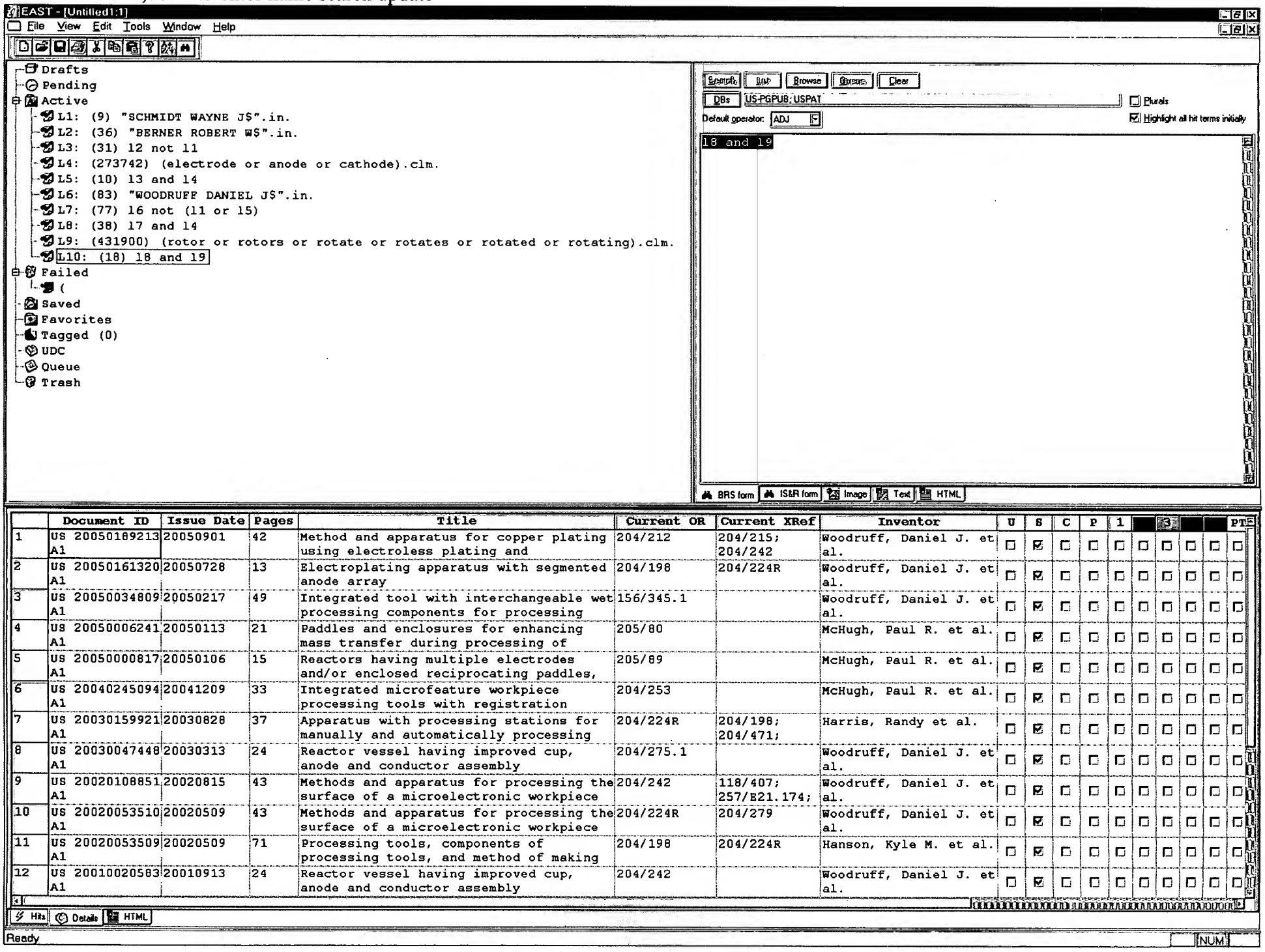
12/2005 08/680,067 inventor name search update



	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	1	3	PT
1	US 20050189213 A1	20050901	42	Method and apparatus for copper plating using electroless plating and	204/212	204/215; 204/242	Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐
2	US 20050161320 A1	20050728	13	Electroplating apparatus with segmented anode array	204/198	204/224R	Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐
3	US 20050034809 A1	20050217	49	Integrated tool with interchangeable wet processing components for processing	156/345.1		Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐
4	US 20050006241 A1	20050113	21	Paddles and enclosures for enhancing mass transfer during processing of	205/80		McHugh, Paul R. et al.	☐	☑	☐	☐	☐	☐	☐
5	US 20050000817 A1	20050106	15	Reactors having multiple electrodes and/or enclosed reciprocating paddles,	205/89		McHugh, Paul R. et al.	☐	☑	☐	☐	☐	☐	☐
6	US 20040245094 A1	20041209	33	Integrated microfeature workpiece processing tools with registration	204/253		McHugh, Paul R. et al.	☐	☑	☐	☐	☐	☐	☐
7	US 20030159921 A1	20030828	37	Apparatus with processing stations for manually and automatically processing	204/224R	204/198; 204/471;	Harris, Randy et al.	☐	☑	☐	☐	☐	☐	☐
8	US 20030047448 A1	20030313	24	Reactor vessel having improved cup, anode and conductor assembly	204/275.1		Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐
9	US 20020108851 A1	20020815	43	Methods and apparatus for processing the surface of a microelectronic workpiece	204/242	118/407; 257/E21.174;	Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐
10	US 20020053510 A1	20020509	43	Methods and apparatus for processing the surface of a microelectronic workpiece	204/224R	204/279	Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐
11	US 20020053509 A1	20020509	71	Processing tools, components of processing tools, and method of making	204/198	204/224R	Hanson, Kyle M. et al.	☐	☑	☐	☐	☐	☐	☐
12	US 20010020583 A1	20010913	24	Reactor vessel having improved cup, anode and conductor assembly	204/242		Woodruff, Daniel J. et al.	☐	☑	☐	☐	☐	☐	☐

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File View Edit Tools Window Help

- Drafts
- Pending
- Active
  - L1: (56156) (cup or vessel or container).clm.
  - L2: (71140) (electrode or cathode or anode).clm.
  - L3: (3304) l1 and l2
  - L4: (102026) (rotor or rotate or rotates or rotated or rotating or rotation).clm.
  - L5: (342) l3 and l4
  - L6: (416077) (holder or support)
  - L7: (232) l5 and l6
  - L8: (412) weir.clm.
  - L9: (12) l7 and l8
- Failed
- Saved
- Favorites
- Tagged (0)
- UDC
- Queue
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DBs: US-PGPUB

Plurals

Default operator: ADJ

Highlight all hit terms initially

l7 and l8

BRS form | IS&R form | Image | Text | HTML

	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	1	3	PT
1	US 20050161320 A1	20050728	13	Electroplating apparatus with segmented anode array	204/198	204/224R	Woodruff, Daniel J. et al.	☑	☐	☐	☐	☐	☐	☐
2	US 20050061675 A1	20050324		Semiconductor plating system workpiece support having workpiece-engaging	205/123	204/201	Bleck, Martin C. et al.	☑	☐	☐	☐	☐	☐	☐
3	US 20040108212 A1	20040610		Apparatus and methods for transferring heat during chemical processing of	205/80		Graham, Lyndon et al.	☑	☐	☐	☐	☐	☐	☐
4	US 20040055877 A1	20040325		Workpiece processor having processing chamber with improved processing fluid	204/275.1	204/227	Wilson, Gregory J. et al.	☑	☐	☐	☐	☐	☐	☐
5	US 20030217929 A1	20031127		Apparatus and method for regulating fluid flows, such as flows of	205/148		Peace, Steven L.	☑	☐	☐	☐	☐	☐	☐
6	US 20030159921 A1	20030828		Apparatus with processing stations for manually and automatically processing	204/224R	204/198; 204/471;	Harris, Randy et al.	☑	☐	☐	☐	☐	☐	☐
7	US 20030079989 A1	20030501		Apparatus and method for deposition of an electrophoretic emulsion	204/471	204/199; 204/275.1;	Klocke, John et al.	☑	☐	☐	☐	☐	☐	☐
8	US 20030057093 A1	20030327		Apparatus and method for deposition of an electrophoretic emulsion	204/471	204/242; 204/276	Klocke, John et al.	☑	☐	☐	☐	☐	☐	☐
9	US 20020195352 A1	20021226		Electrochemical treatment of integrated circuit substrates using concentric	205/687	204/232; 204/242	Mayer, Steven T. et al.	☑	☐	☐	☐	☐	☐	☐
10	US 20020125141 A1	20020912		Tuning electrodes used in a reactor for electrochemically processing a	205/96	118/300; 204/228.1	Wilson, Gregory J. et al.	☑	☐	☐	☐	☐	☐	☐
11	US 20020079215 A1	20020627		Workpiece processor having processing chamber with improved processing fluid	204/275.1		Wilson, Gregory J. et al.	☑	☐	☐	☐	☐	☐	☐
12	US 20020029961 A1	20020314		Electro-chemical deposition system	204/198	204/212; 204/228.1;	Dordi, Yezdi et al.	☑	☐	☐	☐	☐	☐	☐

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